Lattice Semiconductor Corporation - M4A5-256/128-10YI Datasheet

Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	4.5V ~ 5.5V
Number of Logic Elements/Blocks	-
Number of Macrocells	256
Number of Gates	-
Number of I/O	128
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m4a5-256-128-10yi

GENERAL DESCRIPTION

The ispMACH™ 4A family from Lattice offers an exceptionally flexible architecture and delivers a superior Complex Programmable Logic Device (CPLD) solution of easy-to-use silicon products and software tools. The overall benefits for users are a guaranteed and predictable CPLD solution, faster time-to-market, greater flexibility and lower cost. The ispMACH 4A devices offer densities ranging from 32 to 512 macrocells with 100% utilization and 100% pin-out retention. The ispMACH 4A families offer 5-V (M4A5-xxx) and 3.3-V (M4A3-xxx) operation.

ispMACH 4A products are 5-V or 3.3-V in-system programmable through the JTAG (IEEE Std. 1149.1) interface. JTAG boundary scan testing also allows product testability on automated test equipment for device connectivity.

All ispMACH 4A family members deliver First-Time-Fit and easy system integration with pin-out retention after any design change and refit. For both 3.3-V and 5-V operation, ispMACH 4A products can deliver guaranteed fixed timing as fast as 5.0 ns t_{PD} and 182 MHz f_{CNT} through the SpeedLocking feature when using up to 20 product terms per output (Table 2).

Table 2. ispMACH 4A Speed Grades

Device	Speed Grade							
	-5	-55	-6	-65	-7	-10	-12	-14
M4A3-32 M4A5-32	C				C, I	C, I	I	
M4A3-64/32 M4A5-64/32		C			C, I	C, I	I	
M4A3-64/64		C			C, I	C, I	I	
M4A3-96 M4A5-96		C			C, I	C, I	I	
M4A3-128 M4A5-128		C			C, I	C, I	I	
M4A3-192 M4A5-192			C		C, I	C, I	I	
M4A3-256/128		C		C	C, I	C, I	I	
M4A5-256/128				C	C	C, I	I	
M4A3-256/192 M4A3-256/160					C	C, I	I	
M4A3-384				C		C, I	C, I	I
M4A3-512					C	C, I	C, I	I

Note:

1. *C = Commercial, I = Industrial*

Product-Term Array

The product-term array consists of a number of product terms that form the basis of the logic being implemented. The inputs to the AND gates come from the central switch matrix (Table 5), and are provided in both true and complement forms for efficient logic implementation.

Table 5. PAL Block Inputs

Device	Number of Inputs to PAL Block
M4A3-32/32 and M4A5-32/32	33
M4A3-64/32 and M4A5-64/32	33
M4A3-64/64	33
M4A3-96/48 and M4A5-96/48	33
M4A3-128/64 and M4A5-128/64	33
M4A3-192/96 and M4A5-192/96	34
M4A3-256/128 and M4A5-256/128	34
M4A3-256/160 and M4A3-256/192	36
M4A3-384	36
M4A3-512	36

Logic Allocator

Within the logic allocator, product terms are allocated to macrocells in “product term clusters.” The availability and distribution of product term clusters are automatically considered by the software as it fits functions within a PAL block. The size of a product term cluster has been optimized to provide high utilization of product terms, making complex functions using many product terms possible. Yet when few product terms are used, there will be a minimal number of unused—or wasted—product terms left over. The product term clusters available to each macrocell within a PAL block are shown in Tables 6 and 7.

Each product term cluster is associated with a macrocell. The size of a cluster depends on the configuration of the associated macrocell. When the macrocell is used in synchronous mode (Figure 2a), the basic cluster has 4 product terms. When the associated macrocell is used in asynchronous mode (Figure 2b), the cluster has 2 product terms. Note that if the product term cluster is routed to a different macrocell, the allocator configuration is not determined by the mode of the macrocell actually being driven. The configuration is always set by the mode of the macrocell that the cluster will drive if not routed away, regardless of the actual routing.

In addition, there is an extra product term that can either join the basic cluster to give an extended cluster, or drive the second input of an exclusive-OR gate in the signal path. If included with the basic cluster, this provides for up to 20 product terms on a synchronous function that uses four extended 5-product-term clusters. A similar asynchronous function can have up to 18 product terms.

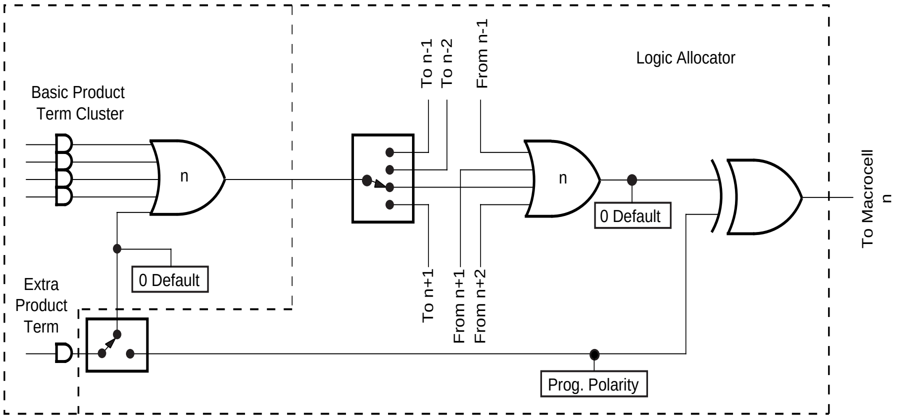
When the extra product term is used to extend the cluster, the value of the second XOR input can be programmed as a 0 or a 1, giving polarity control. The possible configurations of the logic allocator are shown in Figures 3 and 4.

Table 6. Logic Allocator for All ispMACH 4A Devices (except M4A(3,5)-32/32)

Output Macrocell	Available Clusters	Output Macrocell	Available Clusters
M_0	C_0, C_1, C_2	M_8	C_7, C_8, C_9, C_{10}
M_1	C_0, C_1, C_2, C_3	M_9	C_8, C_9, C_{10}, C_{11}
M_2	C_1, C_2, C_3, C_4	M_{10}	C_9, C_{10}, C_{11}, C_{12}
M_3	C_2, C_3, C_4, C_5	M_{11}	C_{10}, C_{11}, C_{12}, C_{13}
M_4	C_3, C_4, C_5, C_6	M_{12}	C_{11}, C_{12}, C_{13}, C_{14}
M_5	C_4, C_5, C_6, C_7	M_{13}	C_{12}, C_{13}, C_{14}, C_{15}
M_6	C_5, C_6, C_7, C_8	M_{14}	C_{13}, C_{14}, C_{15}
M_7	C_6, C_7, C_8, C_9	M_{15}	C_{14}, C_{15}

Table 7. Logic Allocator for M4A(3,5)-32/32

Output Macrocell	Available Clusters	Output Macrocell	Available Clusters
M_0	C_0, C_1, C_2	M_8	C_8, C_9, C_{10}
M_1	C_0, C_1, C_2, C_3	M_9	C_8, C_9, C_{10}, C_{11}
M_2	C_1, C_2, C_3, C_4	M_{10}	C_9, C_{10}, C_{11}, C_{12}
M_3	C_2, C_3, C_4, C_5	M_{11}	C_{10}, C_{11}, C_{12}, C_{13}
M_4	C_3, C_4, C_5, C_6	M_{12}	C_{11}, C_{12}, C_{13}, C_{14}
M_5	C_4, C_5, C_6, C_7	M_{13}	C_{12}, C_{13}, C_{14}, C_{15}
M_6	C_5, C_6, C_7	M_{14}	C_{13}, C_{14}, C_{15}
M_7	C_6, C_7	M_{15}	C_{14}, C_{15}



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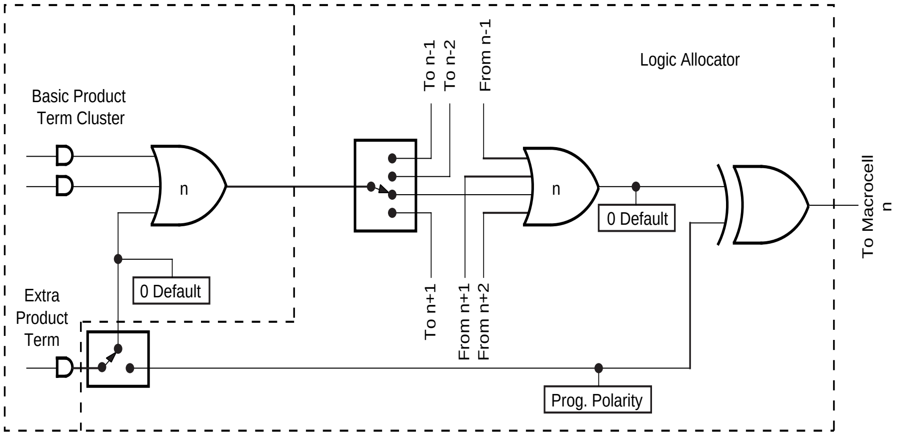
a. Synchronous Mode



b. Asynchronous Mode

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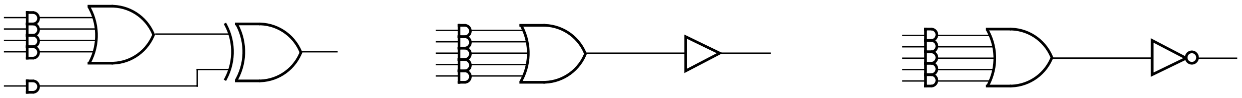
Figure 2. Logic Allocator: Configuration of Cluster “n” Set by Mode of Macrocell “n”



a. Basic cluster with XOR

b. Extended cluster, active high

c. Extended cluster, active low

d. Basic cluster routed away; single-product-term, active high

e. Extended cluster routed away

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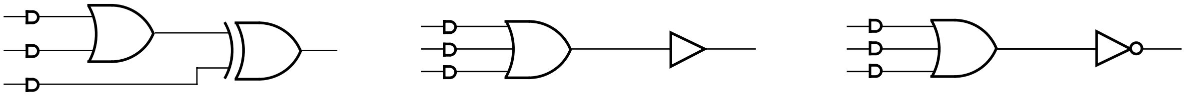
Figure 3. Logic Allocator Configurations: Synchronous Mode



a. Basic cluster with XOR

b. Extended cluster, active high

c. Extended cluster, active low

d. Basic cluster routed away; single-product-term, active high

e. Extended cluster routed away

17466G-008

Figure 4. Logic Allocator Configurations: Asynchronous Mode

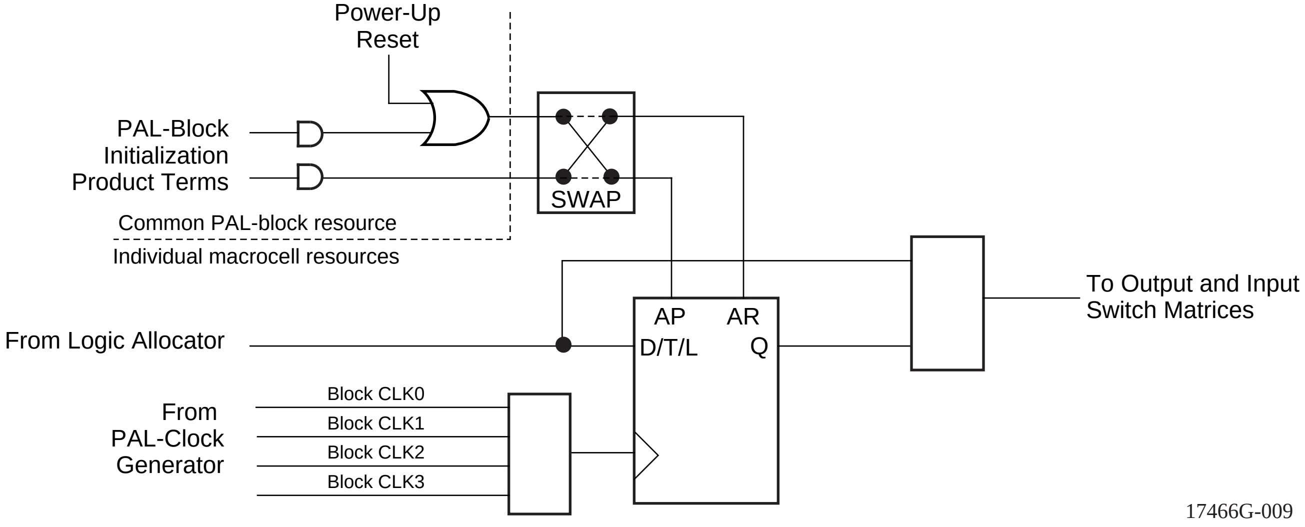
Note that the configuration of the logic allocator has absolutely no impact on the speed of the signal. All configurations have the same delay. This means that designers do not have to decide between optimizing resources or speed; both can be optimized.

If not used in the cluster, the extra product term can act in conjunction with the basic cluster to provide XOR logic for such functions as data comparison, or it can work with the D-,T-type flip-flop to provide for J-K, and S-R register operation. In addition, if the basic cluster is routed to another macrocell, the extra product term is still available for logic. In this case, the first XOR input will be a logic 0. This circuit has the flexibility to route product terms elsewhere without giving up the use of the macrocell.

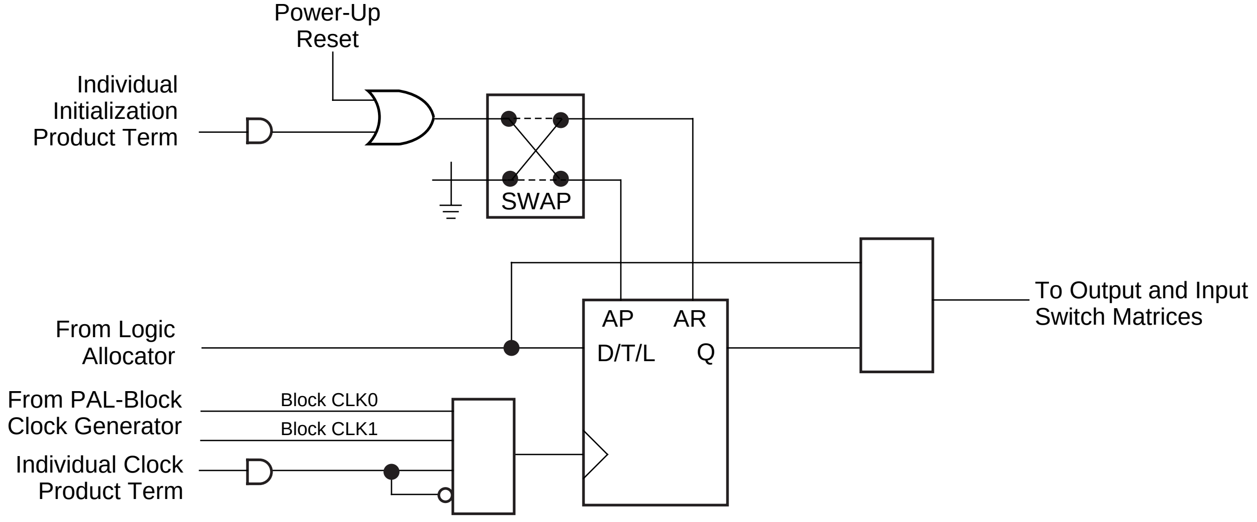
Product term clusters do not “wrap” around a PAL block. This means that the macrocells at the ends of the block have fewer product terms available.

Macrocell

The macrocell consists of a storage element, routing resources, a clock multiplexer, and initialization control. The macrocell has two fundamental modes: synchronous and asynchronous (Figure 5). The mode chosen only affects clocking and initialization in the macrocell.



a. Synchronous mode



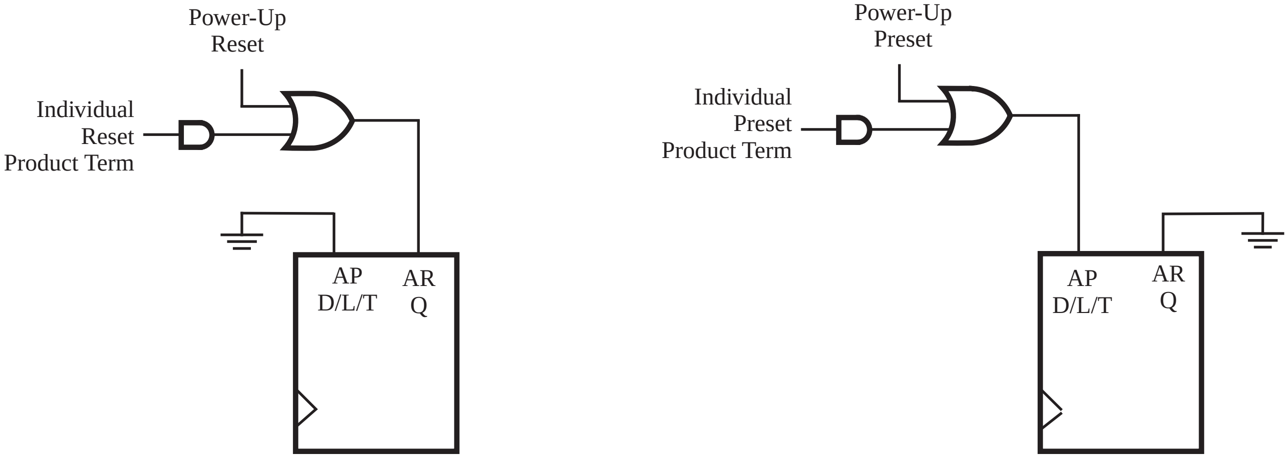
b. Asynchronous mode

17466G-010

Figure 5. Macrocell

In either mode, a combinatorial path can be used. For combinatorial logic, the synchronous mode will generally be used, since it provides more product terms in the allocator.

A reset/preset swapping feature in each macrocell allows for reset and preset to be exchanged, providing flexibility. In asynchronous mode (Figure 8), a single individual product term is provided for initialization. It can be selected to control reset or preset.



a. Reset

b. Preset

17466G-014

17466G-015

Figure 8. Asynchronous Mode Initialization Configurations

Note that the reset/preset swapping selection feature effects power-up reset as well. The initialization functionality of the flip-flops is illustrated in Table 9. The macrocell sends its data to the output switch matrix and the input switch matrix. The output switch matrix can route this data to an output if so desired. The input switch matrix can send the signal back to the central switch matrix as feedback.

Table 9. Asynchronous Reset/Preset Operation

AR	AP	CLK/LE[1]	Q+
0	0	X	See Table 8
0	1	X	1
1	0	X	0
1	1	X	0

Note:

1. *Transparent latch is unaffected by AR, AP*

ispMACH 4A TIMING MODEL

The primary focus of the ispMACH 4A timing model is to accurately represent the timing in a ispMACH 4A device, and at the same time, be easy to understand. This model accurately describes all combinatorial and registered paths through the device, making a distinction between internal feedback and external feedback. A signal uses internal feedback when it is fed back into the switch matrix or block without having to go through the output buffer. The input register specifications are also reported as internal feedback. When a signal is fed back into the switch matrix after having gone through the output buffer, it is using external feedback.

The parameter, t_{BUF}, is defined as the time it takes to go from feedback through the output buffer to the I/O pad. If a signal goes to the internal feedback rather than to the I/O pad, the parameter designator is followed by an “i”. By adding t_{BUF} to this internal parameter, the external parameter is derived. For example, $t_{PD} = t_{PDi} + t_{BUF}$. A diagram representing the modularized ispMACH 4A timing model is shown in Figure 15. Refer to the application note entitled *MACH 4 Timing and High Speed Design* for a more detailed discussion about the timing parameters.

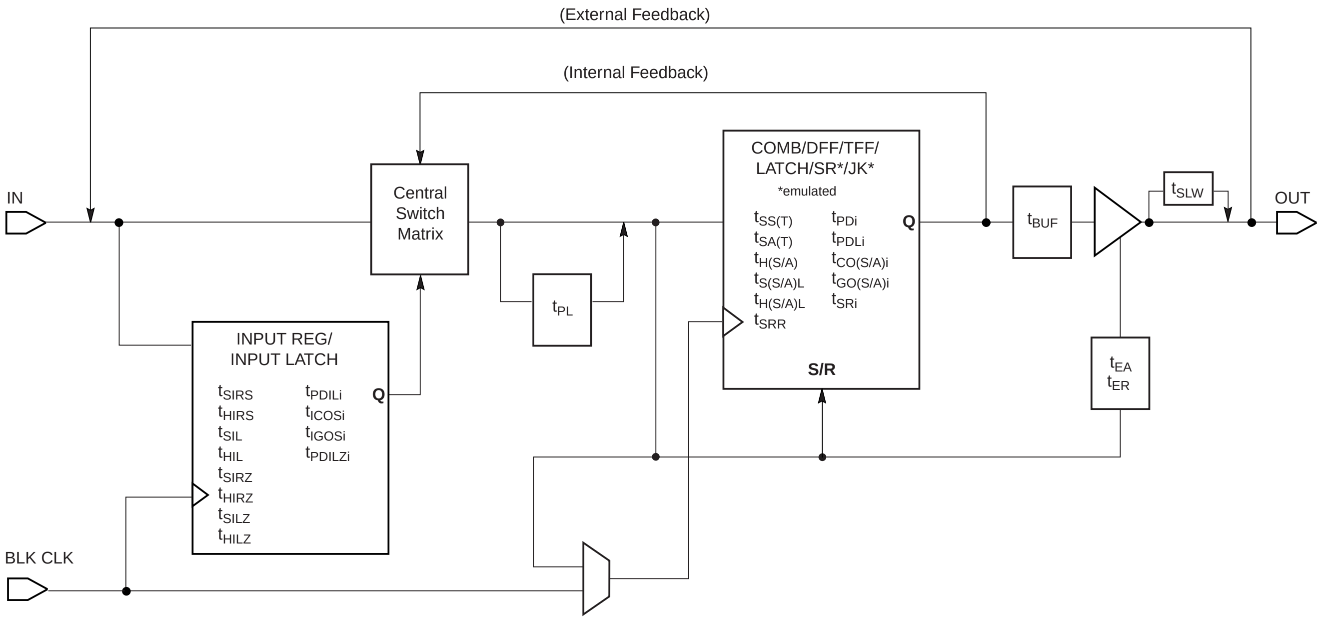


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Figure 15. ispMACH 4A Timing Model

SPEEDLOCKING FOR GUARANTEED FIXED TIMING

The ispMACH 4A architecture allows allocation of up to 20 product terms to an individual macrocell with the assistance of an XOR gate without incurring additional timing delays.

The design of the switch matrix and PAL blocks guarantee a fixed pin-to-pin delay that is independent of the logic required by the design. Other competitive CPLDs incur serious timing delays as product terms expand beyond their typical 4 or 5 product term limits. Speed *and* SpeedLocking combine to give designs easy access to the performance required in today’s designs.

weakly pulled up. For the circuit diagram, please refer to the document entitled *MACH Endurance Characteristics* on the Lattice Data Book CD-ROM or Lattice web site.

POWER MANAGEMENT

Each individual PAL block in ispMACH 4A devices features a programmable low-power mode, which results in power savings of up to 50%. The signal speed paths in the low-power PAL block will be slower than those in the non-low-power PAL block. This feature allows speed critical paths to run at maximum frequency while the rest of the signal paths operate in the low-power mode.

PROGRAMMABLE SLEW RATE

Each ispMACH 4A device I/O has an individually programmable output slew rate control bit. Each output can be individually configured for the higher speed transition (3 V/ns) or for the lower noise transition (1 V/ns). For high-speed designs with long, unterminated traces, the slow-slew rate will introduce fewer reflections, less noise, and keep ground bounce to a minimum. For designs with short traces or well terminated lines, the fast slew rate can be used to achieve the highest speed. The slew rate is adjusted independent of power.

POWER-UP RESET/SET

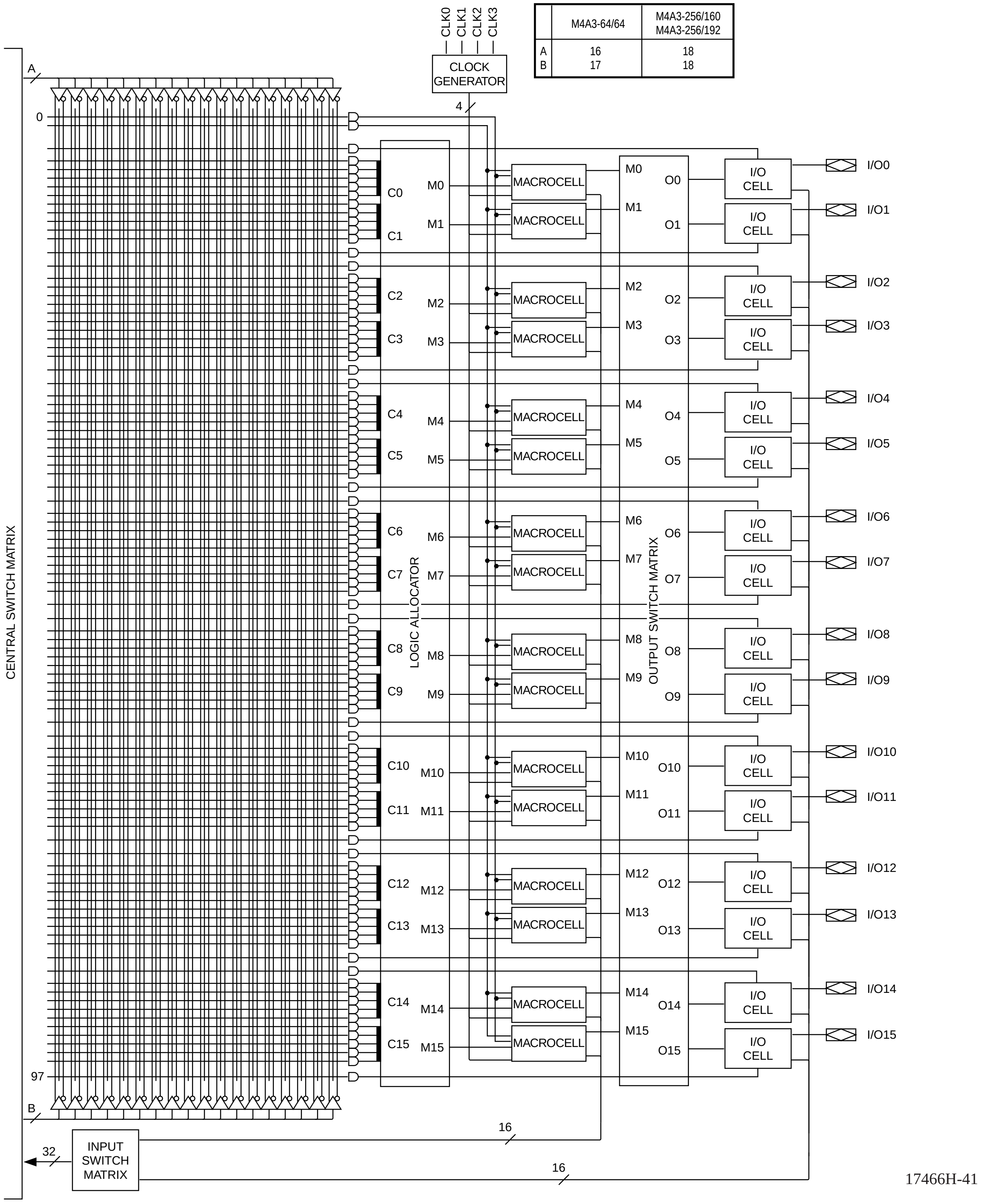
All flip-flops power up to a known state for predictable system initialization. If a macrocell is configured to SET on a signal from the control generator, then that macrocell will be SET during device power-up. If a macrocell is configured to RESET on a signal from the control generator or is not configured for set/reset, then that macrocell will RESET on power-up. To guarantee initialization values, the V_{CC} rise must be monotonic, and the clock must be inactive until the reset delay time has elapsed.

SECURITY BIT

A programmable security bit is provided on the ispMACH 4A devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit defeats readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. Programming and verification are also defeated by the security bit. The bit can only be reset by erasing the entire device.

HOT SOCKETING

ispMACH 4A devices are well-suited for those applications that require hot socketing capability. Hot socketing a device requires that the device, when powered down, can tolerate active signals on the I/Os and inputs without being damaged. Additionally, it requires that the effects of the powered-down MACH devices be minimal on active signals.



	M4A3-64/64	M4A3-256/160 M4A3-256/192
A	16	18
B	17	18

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Figure 17. PAL Block for ispMACH 4A Devices with 1:1 Macrocell-I/O Cell Ratio (except M4A (3,5)-32/32)

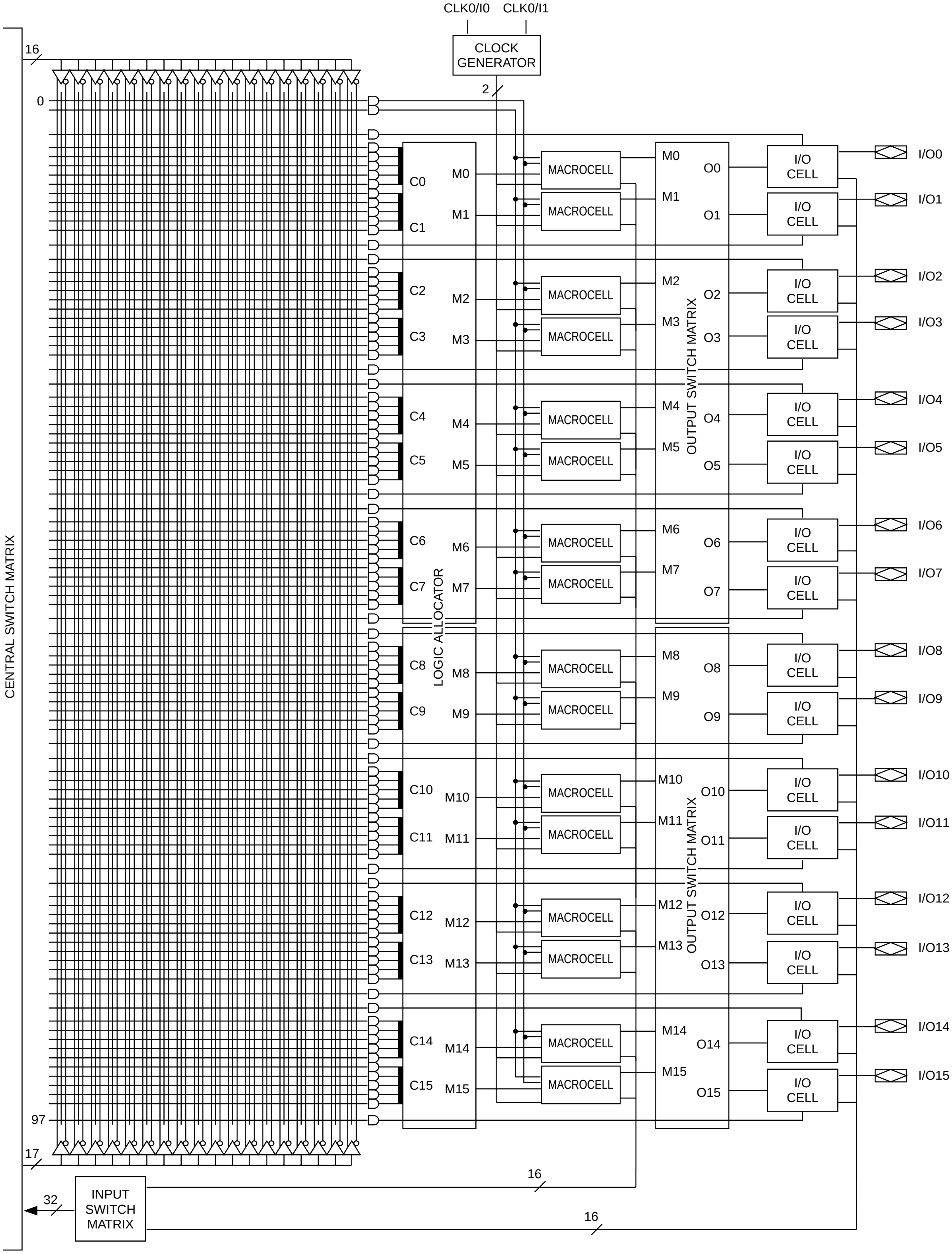
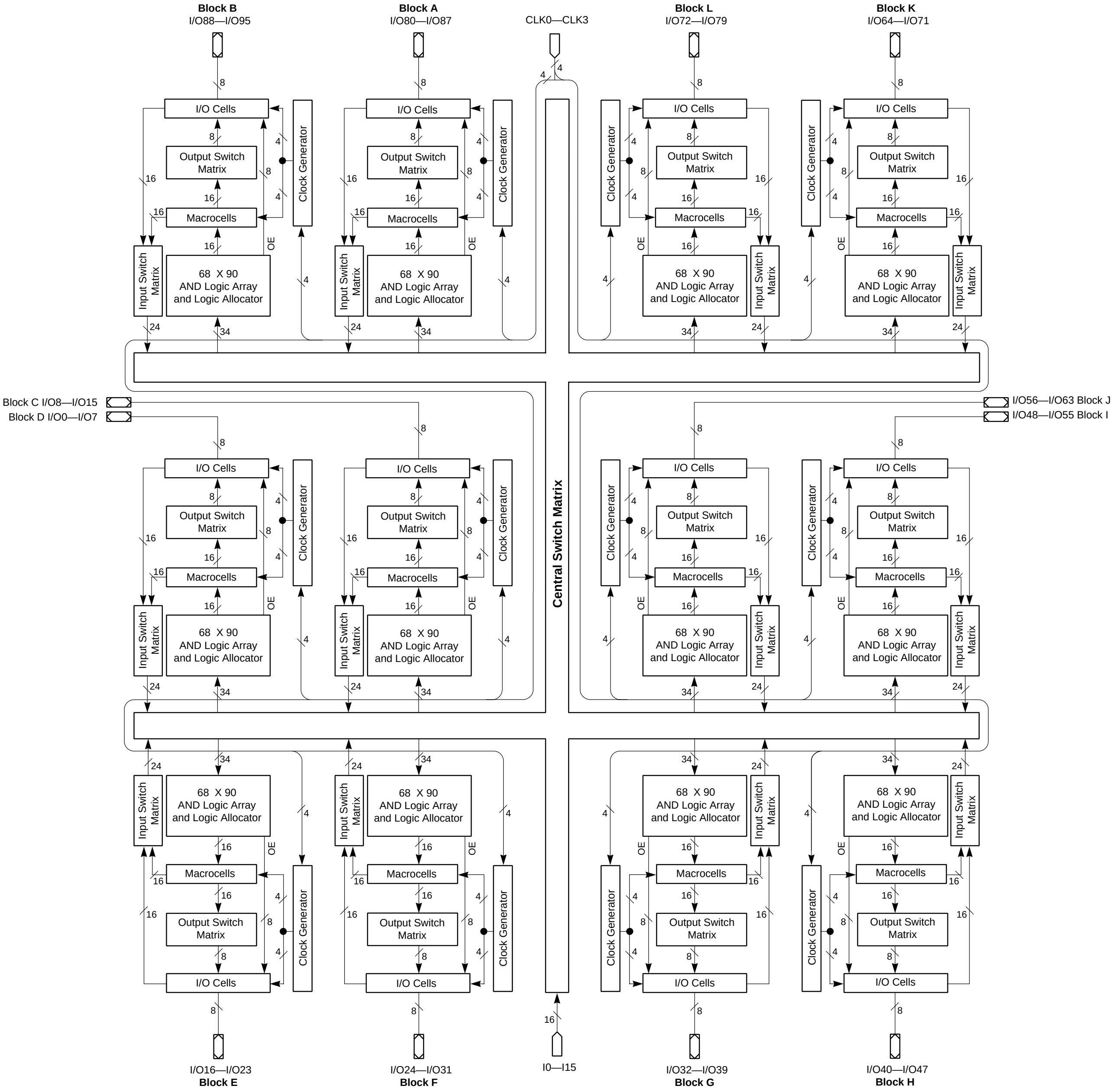


Figure 18. PAL Block for M4A (3,5)-32/32

17466H-042

BLOCK DIAGRAM – M4A(3,5)-192/96



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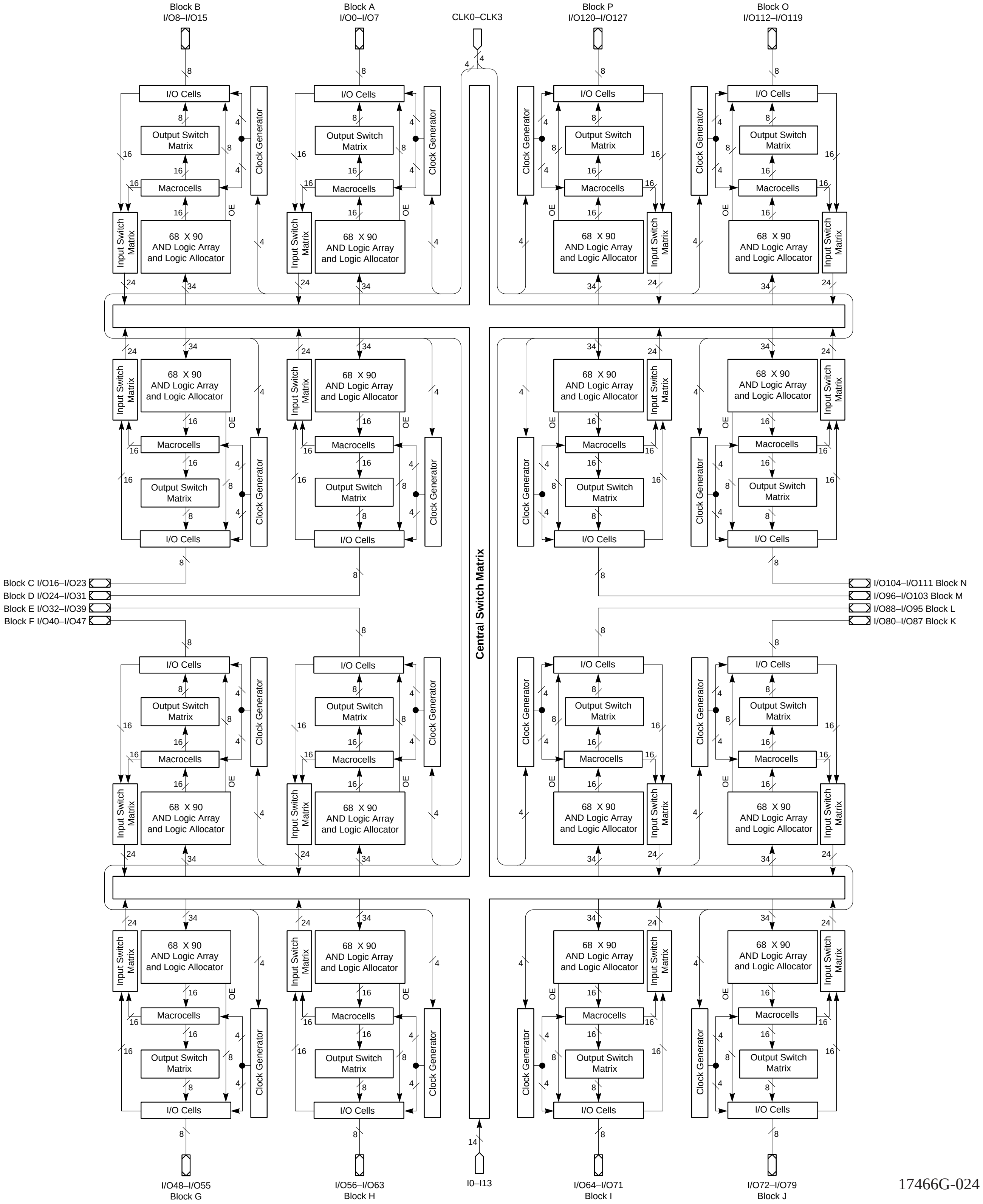
BLOCK DIAGRAM – M4A(3,5)-256/128



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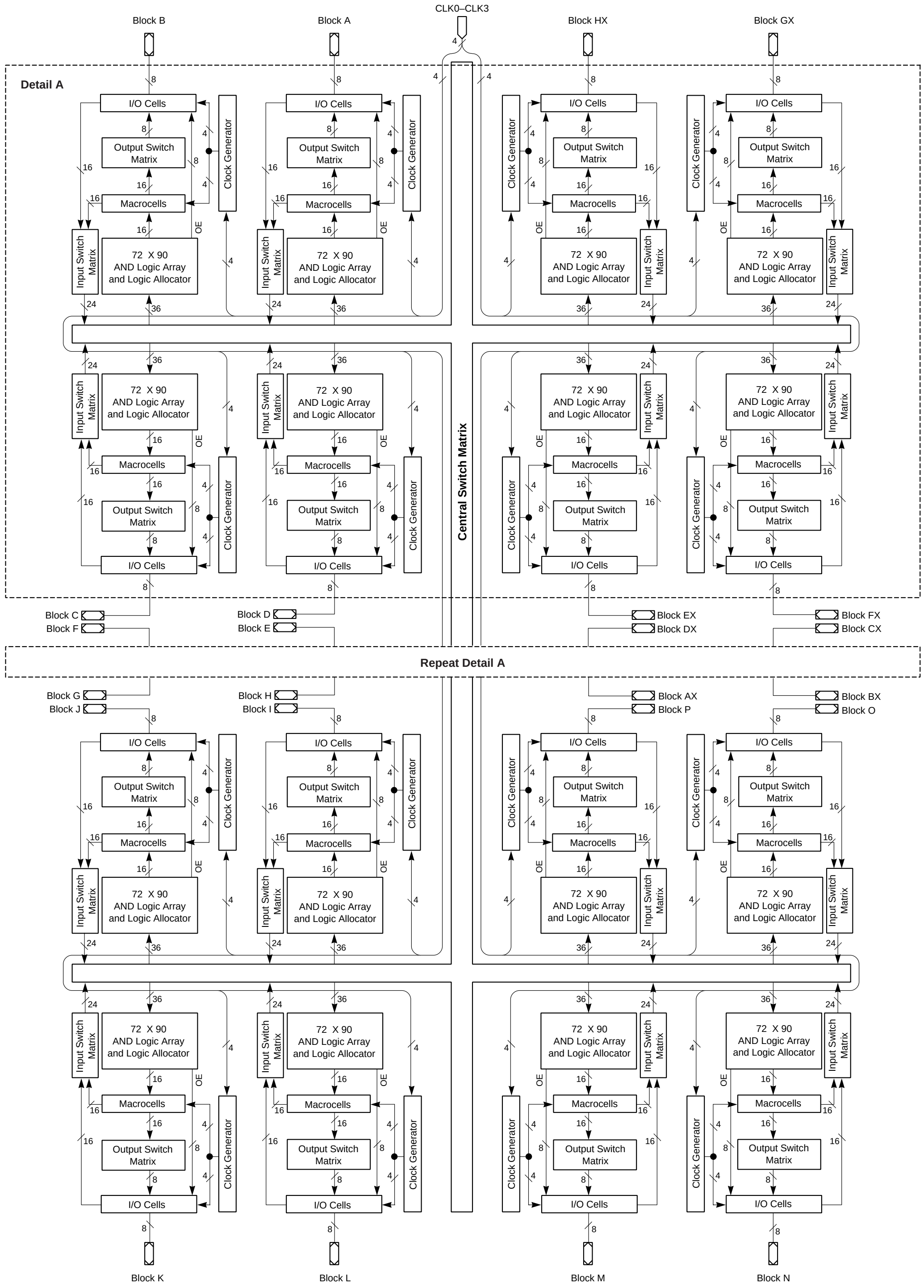
BLOCK DIAGRAM – M4A3-384/160, M4A3-384/192



17466G-067

ABSOLUTE MAXIMUM RATINGS

M4A3

Storage Temperature . . . . -65°C to +150°C

Ambient Temperature
with Power Applied. . . . .-55°C to +100°C

Device Junction Temperature. . . . .+130°C

Supply Voltage
with Respect to Ground . . . .-0.5 V to +4.5 V

DC Input Voltage . . . . -0.5 V to 6.0 V

Static Discharge Voltage . . . . 2000 V

Latchup Current (T_A = -40°C to +85°C) . . . . .200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)
Operating in Free Air . . . . 0°C to +70°C

Supply Voltage (V_{CC})
with Respect to Ground. . . . . +3.0 V to +3.6 V

Industrial (I) Devices

Ambient Temperature (T_A)
Operating in Free Air . . . .-40°C to +85°C

Supply Voltage (V_{CC})
with Respect to Ground. . . . . +3.0 V to +3.6 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

3.3-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions		Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	V_{CC} = Min V_{IN} = V_{IH} or V_{IL}	I_{OH} = –100 µA	V_{CC} – 0.2			V
			I_{OH} = –3.2 mA	2.4			V
V_{OL}	Output LOW Voltage	V_{CC} = Min V_{IN} = V_{IH} or V_{IL} (Note 1)	I_{OL} = 100 µA			0.2	V
			I_{OL} = 24 mA			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs		2.0		5.5	V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs		–0.3		0.8	V
I_{IH}	Input HIGH Leakage Current	V_{IN} = 3.6 V, V_{CC} = Max (Note 2)				5	µA
I_{IL}	Input LOW Leakage Current	V_{IN} = 0 V, V_{CC} = Max (Note 2)				–5	µA
I_{OZH}	Off-State Output Leakage Current HIGH	V_{OUT} = 3.6 V, V_{CC} = Max V_{IN} = V_{IH} or V_{IL} (Note 2)				5	µA
I_{OZL}	Off-State Output Leakage Current LOW	V_{OUT} = 0 V, V_{CC} = Max V_{IN} = V_{IH} or V_{IL} (Note 2)				–5	µA
I_{SC}	Output Short-Circuit Current	V_{OUT} = 0.5 V, V_{CC} = Max (Note 3)		–15		–160	mA

Notes:

1. *Total I_{OL} for one PAL block should not exceed 64 mA.*
2. *I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).*
3. *Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.*

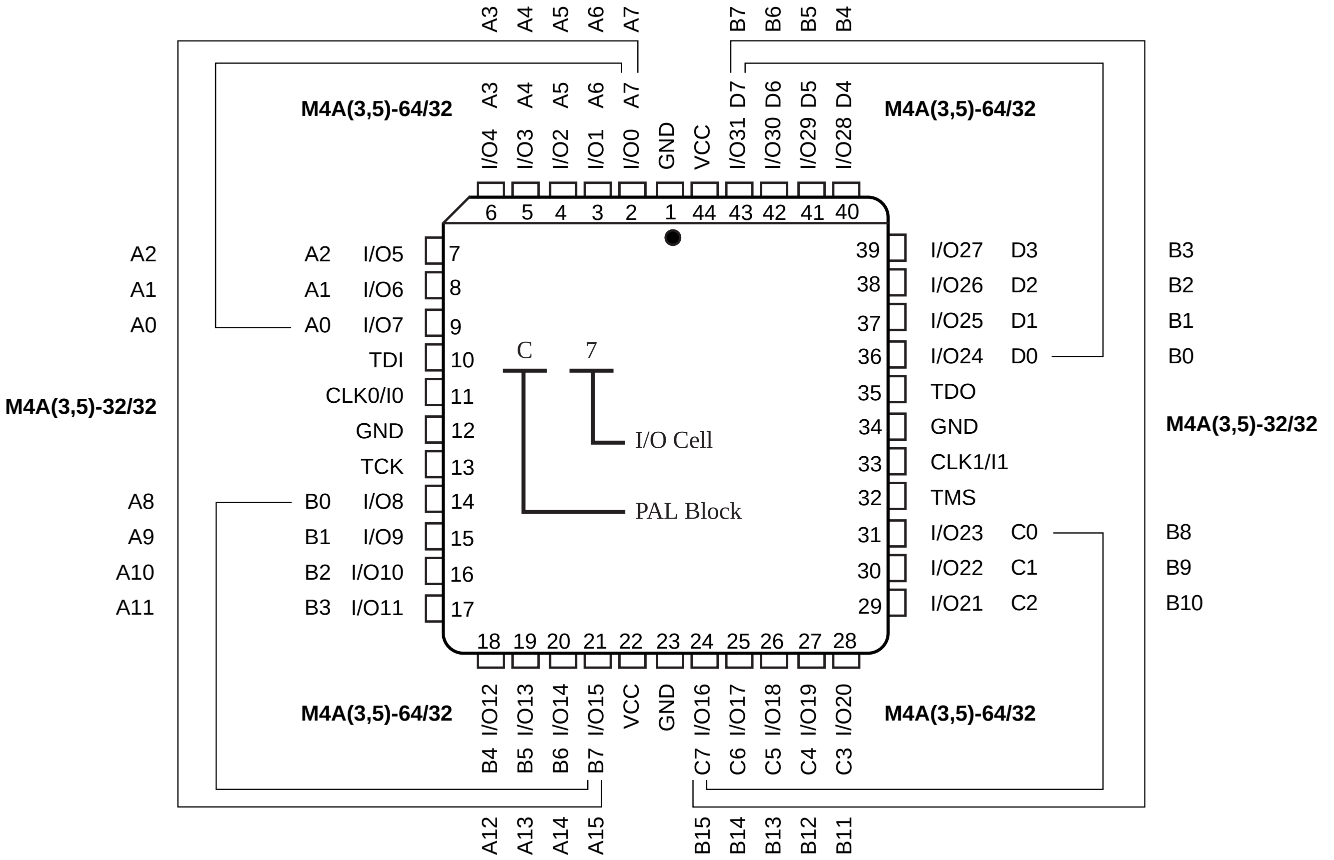
Notes:

1. *See "MACH Switching Test Circuit" document on the Literature Download page of the Lattice web site.*
2. *This parameter does not apply to flip-flops in the emulated mode since the feedback path is required for emulation.*

44-PIN PLCC CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View

44-Pin PLCC



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PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

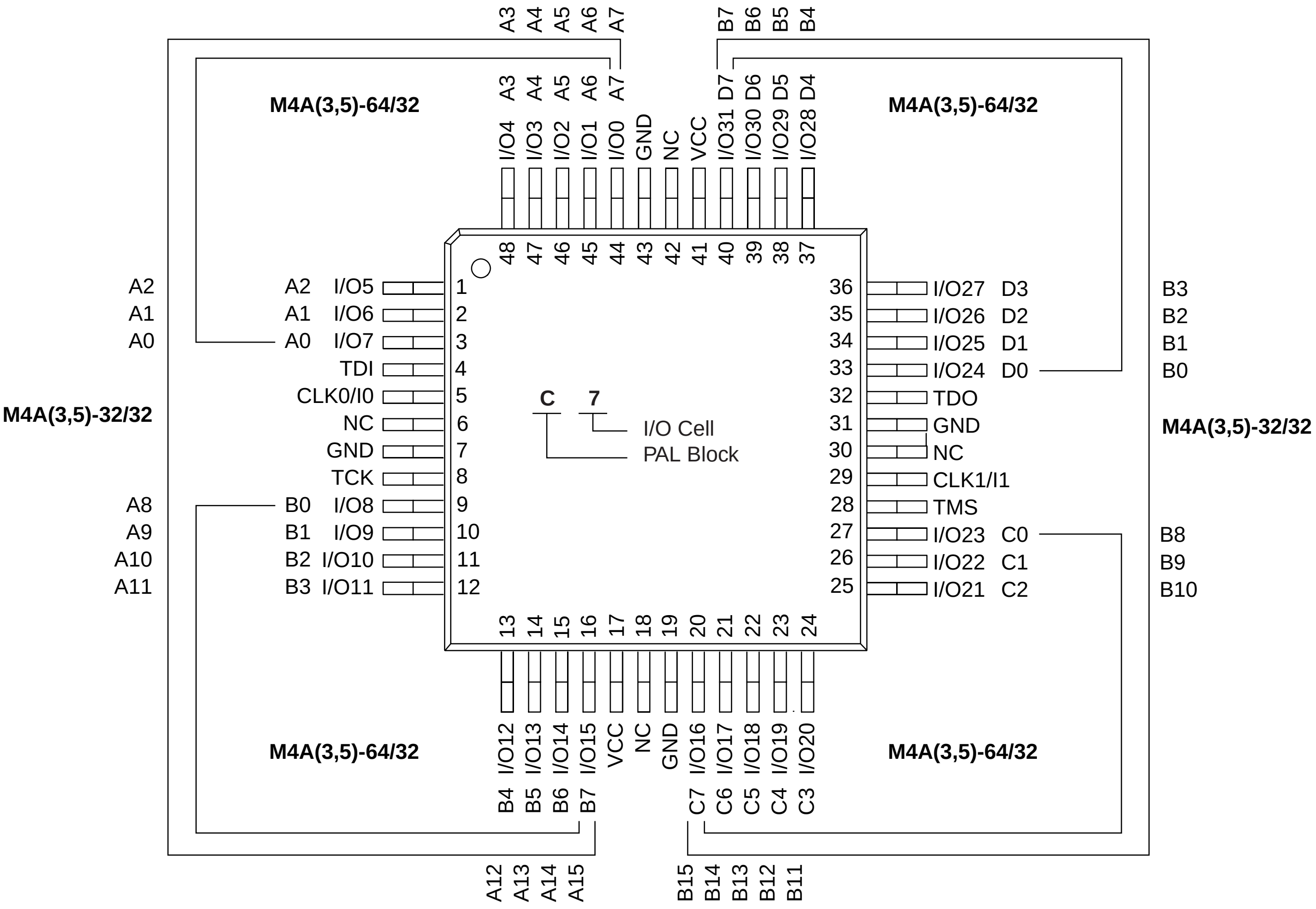
TMS = Test Mode Select

TDO = Test Data Out

48-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View

48-Pin TQFP (1.4mm Thickness)



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PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

NC = No Connect

TDI = Test Data In

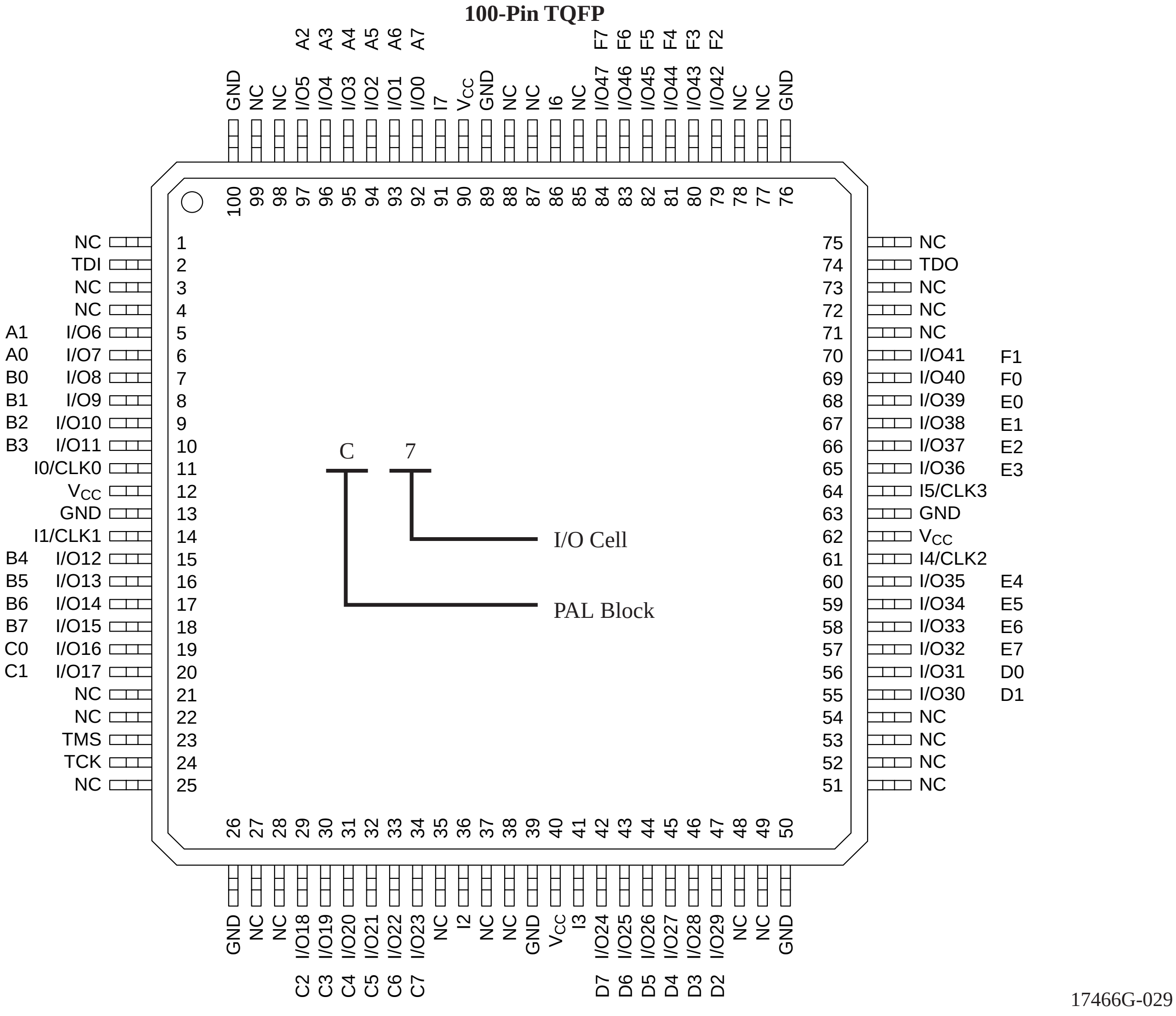
TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

100-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-96/48)

Top View



PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I = Input

I/O = Input/Output

V$_{CC}$ = Supply Voltage

NC = No Connect

TDI = Test Data In

TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

256-BALL BGA CONNECTION DIAGRAM - (M4A3-384/192)

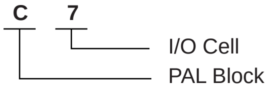
Bottom View

256-Ball BGA

	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	GND	I/O11 FX7	GND	I/O44 FX6	I/O58 CX6	GND	I/O70 CX2	I/O76 DX6	GND	GND	GND	GND	I/O108 AX5	I/O116 BX0	GND	I/O128 BX7	I/O134 O3	GND	GND	GND	**A**
B	GND	I/O12 GX7	I/O28 FX5	I/O45 FX3	I/O59 CX7	I/O64 CX5	I/O71 CX3	I/O77 DX7	I/O84 DX5	I/O90 DX2	I/O96 AX0	I/O102 AX3	I/O109 AX6	I/O117 BX1	I/O122 BX4	I/O129 BX6	I/O135 O4	I/O148 O6	I/O164 O7	GND	**B**
C	I/O0 GX6	I/O13 GX5	VCC	I/O46 FX4	I/O60 FX2	I/O65 FX1	I/O72 CX4	I/O78 CX0	I/O85 DX4	I/O91 DX1	I/O97 AX1	I/O103 AX4	I/O110 BX2	I/O118 BX5	I/O123 O0	I/O130 O1	I/O136 O5	VCC	I/O165 N7	I/O181 N6	**C**
D	I/O1 EX7	I/O14 GX3	I/O29 GX4	VCC	VCC	I/O66 FX0	VCC	I/O79 CX1	I/O86 DX3	I/O92 DX0	I/O98 AX2	I/O104 AX7	I/O111 B3X	VCC	I/O124 O2	VCC	VCC	I/O149 N4	I/O166 N5	I/O182 P7	**D**
E	I/O2 EX0	I/O15 GX0	I/O30 GX1	TDI													TDO	I/O150 N2	I/O167 N3	I/O183 P6	**E**
F	GND	I/O16 EX1	I/O31 EX6	I/O47 GX2													I/O137 N1	I/O151 N0	I/O168 P5	GND	**F**
G	I/O3 HX6	I/O17 EX4	I/O32 EX5	VCC													VCC	I/O152 P4	I/O169 P3	I/O184 M7	**G**
H	GND	I/O18 HX5	I/O33 EX2	I/O48 EX3													I/O138 P2	I/O153 P1	I/O170 P0	GND	**H**
J	I/O4 HX0	I/O19 HX1	I/O34 HX4	I/O49 HX7													I/O139 M6	I/O154 M5	I/O171 M4	I/O185 M3	**J**
K	GND	CLK3	I/O35 HX2	I/O50 HX3													I/O140 M0	I/O155 M1	CLK2	I/O186 M2	**K**
L	I/O5 A2	CLK0	I/O36 A0	I/O51 A1													I/O141 L3	I/O156 L4	CLK1	GND	**L**
M	I/O6 A4	I/O20 A3	I/O37 A5	I/O52 A6													I/O142 L6	I/O157 L5	I/O172 L0	I/O187 L1	**M**
N	GND	I/O21 A7	I/O38 D0	I/O53 D1													I/O143 I5	I/O158 I0	I/O173 L7	GND	**N**
P	I/O7 D2	I/O22 D3	I/O39 D4	VCC													VCC	I/O159 I4	I/O174 I1	I/O188 L2	**P**
R	GND	I/O23 D5	I/O40 D6	I/O54 D7													I/O144 K5	I/O160 K0	I/O175 I3	GND	**R**
T	I/O8 B3	I/O24 B0	I/O41 B7	TCK													TMS	I/O161 K4	I/O176 K1	I/O189 I2	**T**
U	I/O9 B4	I/O25 B1	I/O42 B6	VCC	VCC	I/O67 C0	VCC	I/O80 F0	I/O87 E5	I/O93 E2	I/O99 H2	I/O105 H5	I/O112 G0	VCC	I/O125 J1	VCC	VCC	I/O162 K7	I/O177 K2	I/O190 I6	**U**
V	I/O10 B5	I/O26 B2	VCC	I/O55 C5	I/O61 C2	I/O68 C1	I/O73 F4	I/O81 F1	I/O88 E4	I/O94 E1	I/O100 H1	I/O106 H4	I/O113 G1	I/O119 G4	I/O126 J0	I/O131 J2	I/O145 J5	VCC	I/O178 K3	I/O191 I7	**V**
W	GND	I/O27 C7	I/O43 C6	I/O56 C3	I/O62 F7	I/O69 F5	I/O74 F3	I/O82 E7	I/O89 E3	I/O95 E0	I/O101 H0	I/O107 H3	I/O114 H7	I/O120 G3	I/O127 G5	I/O132 G7	I/O146 J4	I/O163 J6	I/O179 J7	GND	**W**
Y	GND	GND	GND	I/O57 C4	I/O63 F6	GND	I/O75 F2	I/O83 E6	GND	GND	GND	GND	I/O115 H6	I/O121 G2	GND	I/O133 G6	I/O147 J3	GND	I/O180 K6	GND	**Y**
	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

PIN DESIGNATIONS

CLK = Clock
GND = Ground
I = Input
I/O = Input/Output
N/C = No Connect
VCC = Supply Voltage
TDI = Test Data In
TCK = Test Clock
TMS = Test Mode Select
TDO = Test Data Out



17466G-046

5V Commercial Combinations		
M4A5-32/32	-5, -7, -10,	JC, VC, VC48
M4A5-64/32	-55, -7, -10	JC, VC, VC48
M4A5-96/48		VC
M4A5-128/64		YC, VC
M4A5-192/96	-6, -7, -10	VC
M4A5-256/128	-65, -7, -10	YC

5V Industrial Combinations		
M4A5-32/32	-7, -10, -12	JI, VI, VI48
M4A5-64/32	-7, -10, -12	JI, VI, VI48
M4A5-96/48		VI
M4A5-128/64		YI, VI
M4A5-192/96	-7, -10, -12	VI
M4A5-256/128	-10, -12	YI

Lead-free Packaging

3.3V Commercial Combinations		
M4A3-32/32	-5, -7, -10	VNC, VNC48, JNC
M4A3-64/32	-55, -7, -10	VNC, VNC48, JNC
M4A3-64/64		VNC
M4A3-128/64		VNC
M4A3-192/96	-6, -7, -10	VNC
M4A3-256/128	-55, -7, -10	FANC, YNC
M4A3-256/160	-7, -10	YNC
M4A3-256/192		FANC
M4A3-384/192	-65, -10, -12	FANC
M4A3-512/192	-7, -10, -12	FANC

3.3V Industrial Combinations		
M4A3-32/32	-7, -10, -12	VNI, VNI48, JNI
M4A3-64/32		VNI, VNI48, JNI
M4A3-64/64		VNI
M4A3-128/64		VNI
M4A3-192/96	-10, -12	VNI
M4A3-256/128		FANI, YNI
M4A3-256/160		YNI
M4A3-256/192	-10, -12, -14	FANI
M4A3-384/192		FANI
M4A3-512/192		FANI

5V Commercial Combinations		
M4A5-32/32	-5, -7, -10	VNC, VNC48, JNC
M4A5-64/32	-55, -7, -10	VNC, VNC48, JNC
M4A5-96/48		VNC
M4A5-128/64		VNC, YNC
M4A5-192/96	-6, -7, -10	VNC
M4A5-256/128	-65, -7, -10	YNC

5V Industrial Combinations		
M4A5-32/32	-7, -10, -12	VNI, VNI48, JNI
M4A5-64/32		VNI, VNI48, JNI
M4A5-96/48		VNI
M4A5-128/64		VNI, YNI
M4A5-192/96		VNI
M4A5-256/128		YNI

Most ispMACH devices are dual-marked with both Commercial and Industrial grades. The Industrial speed grade is slower, i.e., M4A3-256/128-7YC-10YI

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local Lattice sales office to confirm availability of specific valid combinations and to check on newly released combinations.

Revision History

Date	Version	Change Summary
-	K	Previous Lattice release.
August 2006	L	Updated for lead-free package options.
September 2006	M	Revised M4A3-256/160 208-pin PQFP connection diagram.